To: DIGI-KEY CORPORATION

Issue No. : V-FK-E-514 Date of Issue : June 5, 2012

.

ENGINEERING DRAFT

| Product Description Customer Part Number | : Aluminum Electrolytic Capacitor |
|--|--|
| Product Part Number | : EEVFK1V222M |
| Country of Origin Marking of the Origin Applications Term of Validity | : Japan : Printed on the packaging label : POWER SUPPLY : June 4, 2013 from the date of issue |

 These specifications are temporary specifications. Ask factory for technical specifications before purchase and / or use.

Capacitor Business Unit Industrial Devices Company, Panasonic Corporation

25.Kowata-nishinaka, Uji City, Kyoto, 611-8585, Japan Phone :+81-774-32-1111 Phone :+81-774-33-3209(Direct) Prepared by

Contact Person Signature Name(Prrint) Title

Authorized by Signature Name(Prrint) Title : Engineering Team 4 Engineering Group Aluminum Capacitor Division



: Engineer

Hisao Nagara

: Manager

:

:

No.4628850-8Q91Y



| Engineering Dr | V-FK-E-514 | |
|--|------------------|----------------------|
| | | Page No. Contents |
| | | |
| <u>Contents</u> | | |
| Notice matter | P.1 | |
| Scope | P.2 | |
| Parts Number | P.2 | |
| Parts Lists | P.2 | |
| Dimensions | P.3 | |
| Constructions | P.4 | |
| Marking | P.4 | |
| Lot No. System | P.5 | |
| Standard Rating | P.6 | |
| Performance Characteristics | P.7 ~ P.10 | |
| Other Characteristics | P.10 | |
| Reflow Soldering and Temperature Profile | P.11 | |
| Taping Shape and Dimensions | P.12 | |
| Carrier Tape Packing Method | P.13 ~ P.14 | |
| Package Label Example | P.15 | |
| Application Guidelines | Guidelines-1 ~ 4 | |

| E | Engineering Draft | V-FK-E-514 |
|---|---|-----------------------------------|
| | | 1 |
| Notice matter | | |
| Law and regulation which | are applied | |
| | h the RoHS Directive (Restriction of the use of certain Hazardo and electronic equipment (DIRECTIVE 2002/95/EC). | ous |
| No Ozone Depleting Cher are used in producing this | micals(ODC's), controlled under the Montreal Protocol Agreem s product. | ent, |
| •We do not PBBs or PBDE | Es as brominated flame retardants. | |
| | used for this product are registered as "Known Chemicals" in the mination and Regulation of Manufacture, etc. of Chemical S | |
| | ollowed export related regulations, such as foreign exchange a asion of export of this product Thank you for your consideration | |
| Usage limitation | | |
| home appliances, comput High reliability and safety harm to a human life or p | I to be used for electronics circuits such as audio/visual equipneters and other office equipment, optical equipment and measurare required [be / a possibility that incorrect operation of this property] more. When use is considered by the use, the deliver arately need to be exchanged. | ring equipment. product may do |
| Unless otherwise specifie | d, the product shall conform to JIS 5101-18-2 | |
| Country of origin : JAPAN | | |
| Manufacturing factory : | Aluminum Capacitor Division, Capacitor Business Unit, Industrial Devices Company, Panasonic Corporation. | |
| | 1285, Sakutaguchi, Asada,Yamaguchi City, Yamaguchi 753-8536 Japan | |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |

| Engineering Drat | ft |
|------------------|----|
|------------------|----|

1. Scope

Fixed capacitors for use in electronic equipment, Surface Mount Type Aluminum electrolytic capacitors with non-solid electrolyte.

2. Parts number

| EEV | FK | 1V | 222 | Μ |
|-----|-----|-----|-----|-----|
| 2-1 | 2-2 | 2-3 | 2-4 | 2-5 |

• 2-1 Surface Mount Type Aluminum Electrolytic Capacitor (Lead-Free Products.)

• 2-2 FK series

• 2-3 Rated Voltage Code

| Voltagecode | 1V |
|---------------------|----|
| Rated voltage(V.DC) | 35 |

2-4 Capacitance Code: Indicate capacitance In μF by 3 letters. The first 2 figures are actual values and the third denotes the number of zeros.
 "D" denotes the desired point and all figures are the actual number with "D".

"R" denotes the decimal point and all figures are the actual number with "R".

ex. $0.1\mu F \rightarrow R10$, $10\mu F \rightarrow 100$, $100\mu F \rightarrow 101$

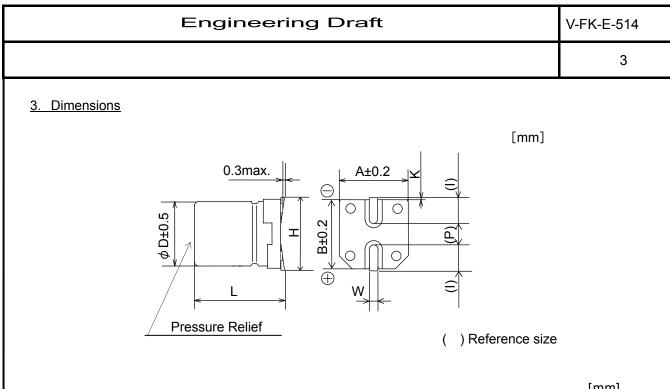
• 2-6 Suffix Code for Appearance: Taping Code

M 44.0mm width (Size code "K")

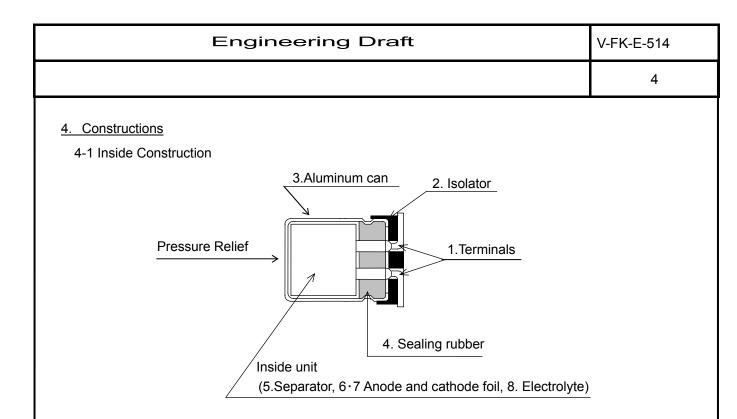
See the drawing in item 11 for the polarity alignment.

Parts lists

| | | | | Tangent of | Leakage | Impedance | Rated Ripple Current |
|------|-----------------|--------|---------|------------|---------|-----------|----------------------|
| Size | Taping Part No. | R.V. | Cap. | Loss Angle | Current | [Ω] | [mA rms] |
| Code | | [V.DC] | [µF] | (tanō) | [µA] | max. | max. |
| | | | | max. | max. | (100kHz) | (100kHz) |
| | | | (120Hz) | (120Hz) | (After | (20°C) | (105°C) |
| | | | (20°C) | (20°C) | 2 min.) | | |
| K21 | EEVFK1V222M | 35 | 2200 | 0.14 | 770.0 | 0.025 | 2740 |
| | | | | | | | |



| Size Code | D | L | A,B | Н | I | W | Р | K |
|-----------|----|------|------|---------|-----|---------|-----|----------|
| K21 | 18 | 21.5 | 19.0 | 21.0max | 6.7 | 1.2±0.3 | 6.7 | 0.70±0.3 |



4-2 Construction parts

| | Parts | Materials | | Parts | Materials |
|---|----------------|----------------------------------|---|--------------|--|
| 1 | Terminal | Tinned Copper-Clad Steel wire | 5 | Separator | Cellulose |
| 2 | Isolator | Thermo-plastic Resin | 6 | Anode Foil | High Purity Aluminum Foil |
| 3 | Aluminum Can | Aluminum | 7 | Cathode Foil | Aluminum Foil |
| 4 | Sealing Rubber | Synthetic rubber (IIR) | 8 | Electrolyte | Organic Solvent , Organic Acid (No Quaternary Salt) |

5. Marking

Marking Color : BLACK

Following items shall be marked on the body of Capacitor.

- a) Rated Voltage Mark
- b) Capacitance
- c) Negative Polarity

Rated Voltage Mark

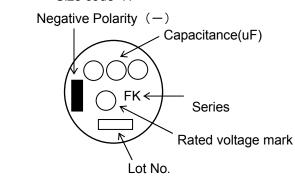
35V

V

d) Series Mark

- e) Lot No. (It indicates to Lot No. System)
- f) Mark for Lead-Free Products. (Size code B to G only)

Size code "H"



| JUDT No. SYSTEM For those made in JAPAN (Chip Type) Size Code (H13~K21) Indicating that the product was produced in 1, Mar. 20 under a line B day(A to Z for 1st~26th and 1 to 5 for 27th~31st) line code in alphabet (A to Z) month (1 to 9 and 0 for October, N for November, D for Decertast number of year (2010=0) production year production year 1:January 7:July A=1 date 1:2010 2:February 8:August B=2 1:2011 1:January 1:January 7:July A=1 date 1=27 date 1:2011 3:March 9:September 2:2012 Indicating with the last digit 5:May N:November Y=25 5=31 6:June D:December | | gineering Dra | ıft | V-FK-E | -514 |
|---|---|--|--|--|------|
| For those made in JAPAN (Chip Type) Size Code (H13~K21) Indicating that the product was produced in 1, Mar. 20 under a line B Indicating that the product was produced in 1, Mar. 20 under a line B day(A to Z for 1st~26th and 1 to 5 for 27th~31st) line code in alphabet (A to Z) month (1 to 9 and O for October, N for November, D for December of year (2010=0) Improduction year production year 9:2009 1:January 7:July A=1 date 1=27 date 9:2009 1:January 7:July A=1 date 1=27 date 9:2010 1:January 7:July A=1 date 1=27 date 9:September 0:O ctober 2:2012 1:April 0:O ctober 2:2012 Indicating with the last digit | | | | | 5 |
| Size Code (H13~K21) Indicating that the product was produced in 1, Mar. 20 under a line B day(A to Z for 1st~26th and 1 to 5 for 27th~31st) line code in alphabet (A to Z) month (1 to 9 and O for October, N for November, D for Decen last number of year (2010=0) <u>production year</u> <u>production month</u> <u>production date</u> 9:2009 1:January 7:July A=1 date 1=27 date 0:2010 2:February 8:August B=2 2=28 1:2011 2:February 8:August B=2 2=28 1:2011 3:March 9:September C=3 3=29 2:2012 4:April O:O ctober ~ 4=30 N:November Y=25 5=31 | OT No. SYSTEM | | | | |
| Size Code (H13~K21) Indicating that the product was produced in 1, Mar. 20 under a line B day(A to Z for 1st~26th and 1 to 5 for 27th~31st) line code in alphabet (A to Z) month (1 to 9 and O for October, N for November, D for Decen- last number of year (2010=0) <u>production year</u> <u>production month</u> <u>production date</u> 9:2009 1:January 7:July A=1 date 1=27 date 0:2010 2:February 8:August B=2 2=28 1:2011 3:March 9:September C=3 3=29 2:2012 4:April O:O ctober ~ 4=30 N:November Y=25 5=31 | or those made in JAPAN (Ch | <u>р Түре)</u> | | | |
| 03B3Indicating that the product was produced in 1, Mar. 20 under a line Bday(A to Z for 1st~26th and 1 to 5 for 27th~31st) line code in alphabet (A to Z) month (1 to 9 and O for October, N for November, D for Decen last number of year (2010=0)production yearproduction monthproduction date 1=27 date9:2009 0:2010 1:2011 2:February 2:2012 1:2011 2:2012 Indicating with the last digit7:July 3:MarchA=1 date 9:September O:O ctober C=31=27 date 3=29 C=3production given the last digit0:O ctober 5:May0:O ctober N:NovemberY=255=31 | Size Code (H13~K21) | | | | |
| 9:2009 1:January 7:July A=1 date 1=27 date 0:2010 2:February 8:August B=2 2=28 1:2011 3:March 9:September C=3 3=29 2:2012 4:April O:October ~ 4=30 Indicating with the last digit 5:May N:November Y=25 5=31 | | B 3 under day(A line cc month | a line B to Z for 1st∼26th and ² ode in alphabet (A to Z) i (1 to 9 and O for Octobe | 1 to 5 for 27th~31st) er, N for November, D for D | |
| 9:2009 1:January 7:July A=1 date 1=27 date 0:2010 2:February 8:August B=2 2=28 1:2011 3:March 9:September C=3 3=29 2:2012 4:April O:October ~ 4=30 Indicating with the last digit 5:May N:November Y=25 5=31 | | | | | |
| | 9:2009 0:2010 1:2011 2:2012 Indicating with the last digi | 1:January7:July2:February8:Augus3:March9:Septe4:AprilO:Octo5:MayN:Nove | A=1 date st B=2 mber C=3 ber ~ mber Y=25 | 1=27 date 2=28 3=29 4=30 | |
| | | | | | |

6. Standard rating

| Nº | Item | | Ratings | | | |
|----|----------------------------|-------------------------|---------|----------------|--------------|--|
| 1 | Category Temperature Range | | | -55°C ∼ +105°C | | |
| 2 | Rated Voltage Range | | 35 V.DC | | | |
| 3 | Capacitance Range | 2200 µF (120Hz 20° | | | (120Hz 20°C) | |
| 4 | Capacitance Tolerance | | | ±20% | (120Hz 20°C) | |
| 5 | Surge Voltage | R.V. | 35 | | | |
| | (V.DC) | S.V. 44 | | | | |
| 6 | Rated Ripple Current | Parts lists and Table 2 | | | | |
| 7 | Impedance | Parts lists | | | | |

V-FK-E-514

7

7. Performance Characteristics

| No | Item | Performance Characteristics | Test |
|----|-----------------|---|---|
| | Leakage Curren | | Series Resistor : $1000\Omega \pm 10\Omega$ |
| ' | Leakage Curren | $1 \ge 1-0.010$ | Applied Voltage : Rated voltage |
| | | [I:Leakage current C:Capacitance] | Measuring : After 2 minutes |
| | | V:Rated voltage | Measuring . Alter 2 minutes |
| 2 | Capacitance | Within the specified capacitance tolerance. | Measuring Frequency : 120Hz±20% |
| 2 | Capacitance | Within the specified capacitance tolerance. | Measuring Circuit : Equivalent series circuit |
| | | | Measuring Voltage : +1.5 V.DC \sim +2 V.DC |
| | | | (≦0.5 V for A.C.) |
| 3 | Tangent of Loss | Less than the value of Partlists. | Measuring Frequency : 120Hz±20% |
| 5 | Angle | | Measuring Circuit : Equivalent series circuit |
| | (tanδ) | | Measuring Voltage : +1.5 V.DC \sim +2 V.DC |
| | (tario) | | (≦0.5 V for A.C.) |
| 4 | Charact- Sten | 2 Impedance Ratio: | (=0.5 V 101 A.C.) |
| | eristics at | Less than the table 1 value of item 8 | Step Test Temperature(°C) Time |
| | High and | ratio against step 1. | $\begin{array}{c c c c c c c c c c c c c c c c c c c $ |
| | - | Leakage Current: | 2 -25°C±3°C ,-40°C±3°C ,-55°C±3°C 30 min |
| | perature | $\leq 800\%$ of the value of item 7.1. | 3 20±2 10 min~15 min |
| | porataro | Capacitance Change: | 4 105±2 30 min |
| | | Within ±25% of the value in step 1. | 5 20±2 10 min~15 min |
| | | Tangent of Loss Angle (tanδ): | Impedance should be measured 120Hz±10%. |
| | | \leq the value of item 7.3. | |
| 5 | Surge | Leakage Current: | Test temperature : 15°C∼35°C |
| | - | \leq the value of item 7.1. | |
| | | Capacitance Change: | Series Protective Resistance : R = $\frac{100 \pm 50}{C}$ |
| | | Within ±15% of initial measured value. | C C |
| | | Tangent of Loss Angle (tanδ): | R: Protective resistance(kΩ) |
| | | \leq the value of item 7.3. | C: Capacitance(µF) |
| | | Appearance: | Test voltage : Surge voltage item 6.5 |
| | | No significant change can be observed. | Applied voltage 1000 cycles of 30s±5s |
| | | | "ON"and 5 min 30 s"OFF". |
| | | | |
| 6 | Robustness of | There is no damage or breakage after test. | After fixing the capacitors, the terminals are |
| | Termination | | pulled in a vertical direction. |
| | (Tensile) | | Load is gradually increased until it reached |
| | | | the value specified below and held for 10 |
| | | | seconds. |
| | | | Pull Strength 10N |
| | | | Keep time 10s±1s |
| | | | |
| | | | |

| No | Item | Performance Characteristics | Test |
|----|---|--|--|
| 7 | Vibration | Capacitance : During test, measured value shall be stabilized.(Measured several times within 30 min. before completion of test) Appearance : No significant change can be observed. Capacitance Change : Within ±5% of initial measured value. | Frequency : 10Hz~55Hz (1 minute per cycle.) Total amplitudes : 1.5 mm Direction and duration of vibration : It is done in the X,Y,Z axis direction for 2 hours each, with a total of 6 hours. |
| 8 | Solderability | More than 95% of the terminal surface shall be covered with new solder. (Exclude the cross-section of cutting lead edge.) | Solder Type : H60A,H60S,or H63A(JIS Z3282) Solder Temperature : 235°C±5°C Immersing Time : 2s±0.5s Immersing Depth : Dip the terminals for Approx 0.5mm~1mm thick Flux : Approx 25% rosin(JIS K5902) in Ethanol(JIS K8101) |
| 9 | Resistance to Soldering heat | Leakage Current : ≦the value of item 7.1. Capacitance Change : Within ±10% of initial measured value. Tangent of Loss Angle (tanδ) : ≦the value of item 7.3. Appearance : No significant change can be observed. | After reflow soldering (item 9) The capacitor shall be left at room temperature for before measurement. |
| 10 | Solvent Resistance of the Marking | There shall be no damage end legibly marked. Marking can be deciphered easily. | Class of Reagent : Isopropyl Alcohol Test Temperature : 20°C~25°C Immersing time : 30s±5s |
| 11 | Damp Heat (steady state) | Leakage Current : ≦the value of item 7.1. Capacitance Change : Within ±15% of initial measured value. Tangent of Loss Angle (tanδ) : ≦120% the value of item 7.3. Appearance : No significant change can be observed. | Test Temperature : 40°C±2°C Relative Humidity : 90%~95% Test Duration : 240hours±8hours After subjected to the test, the capacitors shall be left for 2 hours at room temperature and room humidity prior to the measurement. |

| lo | Item | Performance Characteristics | Test | | | |
|------|--|---|---|---------------------------------|--|--|
| 2 Pr | essure Relief | Pressure relief shall be operated without | A.C. Current Method | | | |
| | any hazardous expulsion or emission of flame. No emission of gas after 30 minutes of the voltage application also meets the specification. | | A.C. Power supply 50Hz or 60Hz (A):A.C. ammeter R:Series resister (X):A.C. voltmeter Cx:Tested capacitor | | | |
| | | | Applied Voltage : | | | |
| | | | A.C. voltage equals to R.V | V. x 0.7 or | | |
| | | | 250 V(rms) whichever is s | | | |
| | | | Capacitance (µF) | D.C. resistance(Ω | | |
| | | | ≦1 | 1000±100 | | |
| | | | >1 ≦10 | 100±10 | | |
| | | | >10 ≦100 | 10±1 | | |
| | | | >100 ≦1000 | 1±0.1 | | |
| | | | >1000 ≦10000 | 0.1±0.01 | | |
| | | | >10000 * | | | |
| | | | * When capacitance is over value of series resistance of the tested capacitor's in • Reverse Voltage Method + D.C. Power supply - (A:D.C. ammeter Cx:Te | equals to the half npedance. | | |
| | | | Nominal Diamether (mm) | D.C. Current(A | | |
| | | | ≤ 22.4 | 1 (const) | | |
| | | | > 22.4 | 10 (const) | | |

| No | ltem | Performance characteristics | Test |
|----|-------------------------------|--|---|
| 13 | 3 Endurance Leakage Current : | | Test Temperature : 105°C±2°C |
| | | \leq the value of item 7.1. | Test Duration : 5000 ⁺⁷² 0 hours |
| | | Capacitance change : | Applied Voltage : Rated voltage |
| | | Within ±30% of initial measured value. | |
| | | Tangent of Loss Aangle (tanδ): | After subjected to the test, the capacitors shall |
| | | \leq 200% of the value of item 7.3. | be left at room temperature and room humidity |
| | | Appearance : | for 2 hours prior to the measurement. |
| | | No significant change can be observed. | |
| 14 | Shelf Life | Leakage Current : | Test Temperature : 105°C±2 °C |
| | | \leq the value of item 7.1. | Test Duration : 1000 ⁺⁴⁸ 0 hours |
| | | Capacitance Change : | |
| | | Within ±30% of initial measured value. | |
| | | Tangent of Loss Angle (tanδ) : | After subjected to the test, D.C. rated |
| | | \leq 200% of the value of item 7.3. | voltage shall be applied to the capacitors for |
| | | Appearance : | 30 minutes as post-test treatment after left |
| | | No significant change can be observed. | at the room temperature and humidity for 2 |
| | | | hours prior to the measurement. |

* Voltage treatment : The rated voltage shall be applied to the capacitors, which are connected to series protective resistors ($1000\Omega \pm 10\Omega$), for 30 minutes as a posttest treatment (performing discharge).

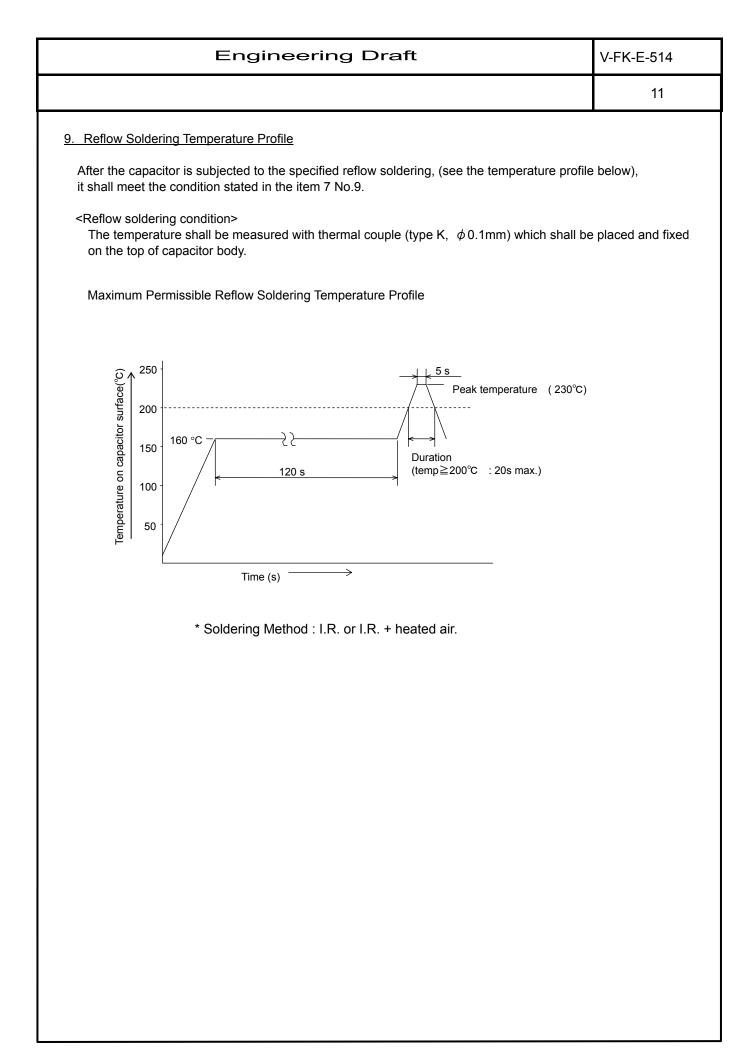
8. Other Characteristics

■ Table 1. Characteristics at low temperature Impedance ratio (at 120Hz)

| R.V.(V D.C.) | 35 |
|------------------|----|
| Z(-25°C)/Z(20°C) | 2 |
| Z(-40°C)/Z(20°C) | 3 |
| Z(-55°C)/Z(20°C) | 3 |

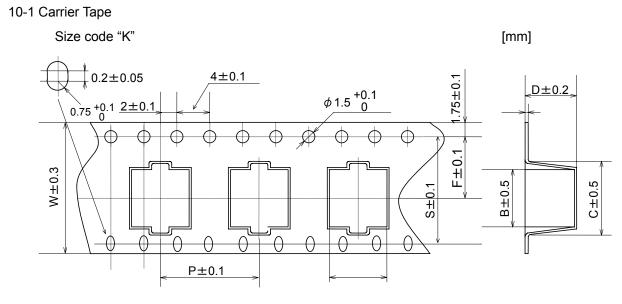
■ Table 2. Frequency Correction Factor of Rated Ripple Current

| | Frequency (Hz) | | | | |
|-------------|----------------|------|------|------|-------|
| | 50,60 | 120 | 1k | 10k | 100k~ |
| Coefficient | 0.70 | 0.75 | 0.90 | 0.95 | 1.00 |





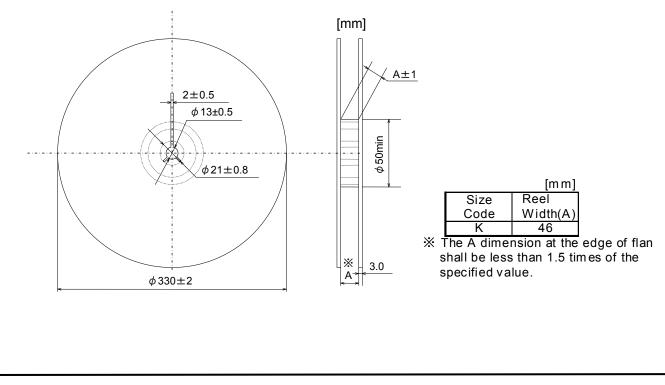
10. Taping

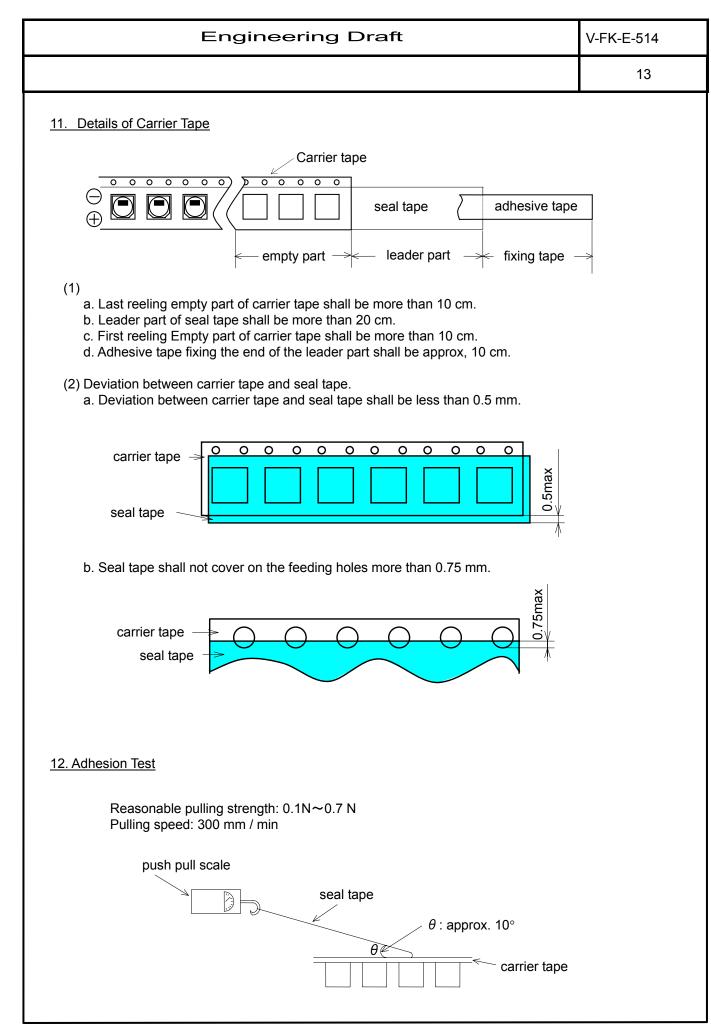


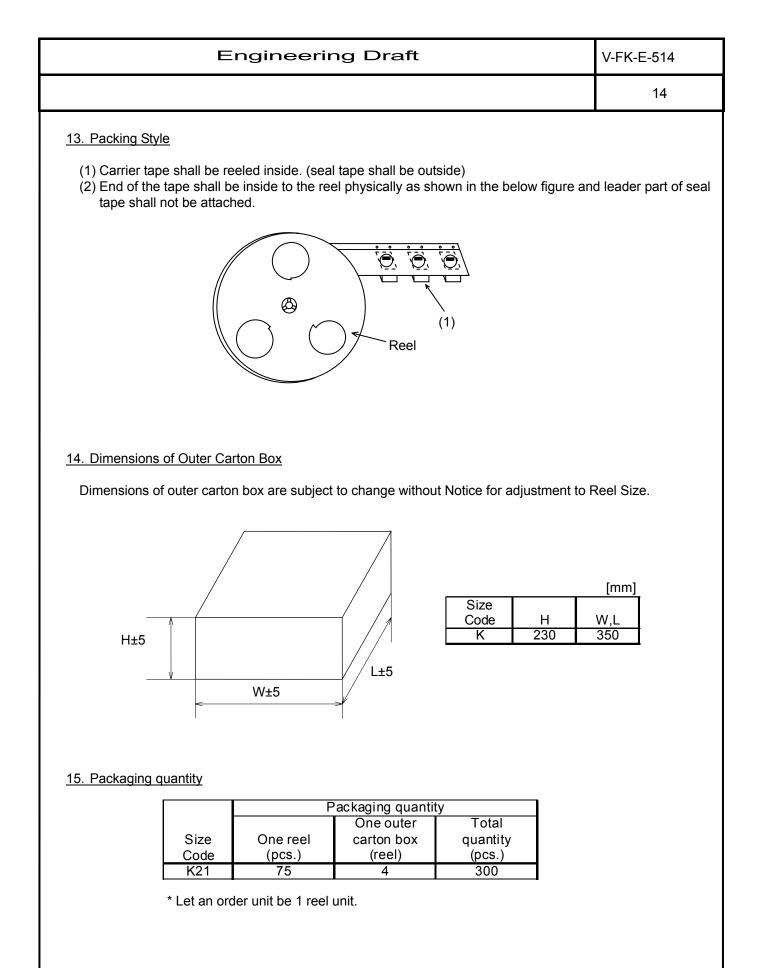
| | | | | | | | | [mm] |
|-----------------------|------|------|------|------|------|------|------|------|
| Size Taping Dimension | | | | | | | | |
| Code | А | В | С | D | F | Р | S | W |
| K21 | 19.5 | 19.5 | 26.0 | 22.5 | 20.2 | 32.0 | 40.4 | 44.0 |

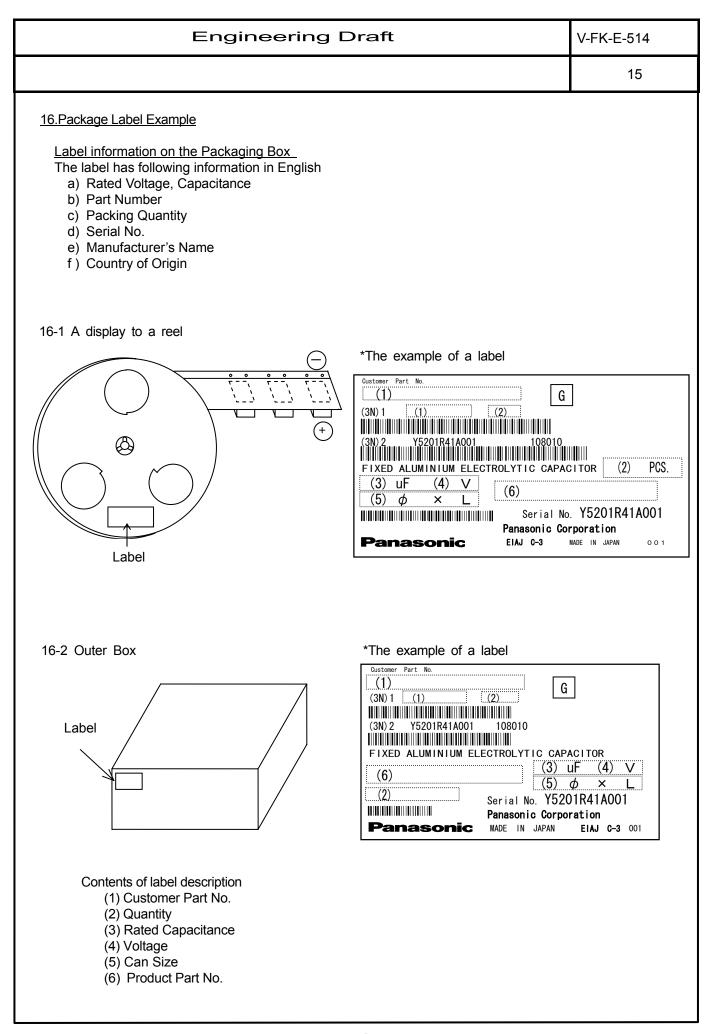
Dimensions of A and B are measured at the bottom of the embossed part.

10-2 Reel









Guideline-ALV-S1-4

Application Guidelines

- * This specification guarantees the quality and performance of the product as individual components.
- Before use, check and evaluate their compatibility with installed in your products.
- * Do not use the products beyond the specifications described in this document.
- * Install the following systems for a failsafe design to ensure safety if these products are to be used in equipment where a defect in these products may cause the loss of human life or other signification damage, such as damage to vehicles (automobile, train, vessel), traffic lights, medical equipment, aerospace equipment, electric heating appliances, combustion/ gas equipment, rotating equipment, and disaster/crime prevention equipment.
 - The system is equipped with a protection circuit and protection device.
 - The system is equipped with a redundant circuit or other system to prevent an unsafe status in the event of a single fault.

* Before using the products, carefully check the effects on their quality and performance, and determined whether or not they can be used. These products are designed and manufactured for general-purpose and standard use in general electronic equipment.

These products are not intended for use in the following special conditions.

- 1. In liquid, such as Water, Oil, Chemicals, or Organic solvent
- 2. In direct sunlight, outdoors, or in dust
- 3. In vapor, such as dew condensation water of resistive element, or water leakage, salty air, or air with a high concentration corrosive gas, such as Cl2, H2S, NH3, SO2, or NO2
- 4. In an environment where strong static electricity or electromagnetic waves exist
- 5. Mounting or placing heat-generating components or inflammables, such as vinyl-coated wires, near these products
- 6. Sealing or coating of these products or a printed circuit board on which these products are mounted, with resin and other material
- 7. Using resolvent, water or water-soluble cleaner for flux cleaning agent after soldering.
 - (In particular, when using water or a water-soluble cleaning agent, be careful not to leave water residues)
- * Please arrange circuit design for preventing impulse or transitional voltage.

Do not apply voltage, which exceeds the full rated voltage when the capacitors receive impulse voltage, instantaneous high voltage, high pulse voltage etc.

* Electrolyte is used in the products. Therefore, misuse can result in rapid deterioration of characteristics and functions of each product. Electrolyte leakage damages printed circuit and affects performance, characteristics, and functions of customer system.

1. Circuit Design

1.1 Operating Temperature and Frequency

Electrical parameters for electrolytic capacitors are normally specified at 20 °C temperature and 120 Hz frequency.

- These parameters vary with changes in temperature and frequency. Circuit designers should take these changes into consideration. (1) Effects of operating temperature on electrical parameters
 - a) At higher temperatures, leakage current and capacitance increase while equivalent series resistance (ESR) decreases.
 - b) At lower temperatures, leakage current and capacitance decrease while equivalent series resistance (ESR) increases.
- (2) Effects of frequency on electrical parameters
 - a) At higher frequencies, capacitance and impedance decrease while tan $\delta\,$ increases.
- b) At lower frequencies, heat generated by ripple current will rise due to an increase in equivalent series resistance (ESR).

1.2 Operating Temperature and Life Expectancy

- (1) Expected life is affected by operating temperature. Generally, each 10 °C reduction in temperature will double the expected life. Use capacitors at the lowest possible temperature below the upper category temperature.
- (2) If operating temperatures exceed the upper category limit, rapid deterioration of electrical parameter will occur and irreversible damage will result.

Check for the maximum capacitor operating temperatures including ambient temperature, internal capacitor temperature rise due to ripple current, and the effects of radiated heat from power transistors, IC's or resistors.

Avoid placing components, which could conduct heat to the capacitor from the back side of the circuit board.

(3) The formula for calculating expected life at lower operating temperatures is as follows ;

$$L_2 = L_1 \times 2^{\frac{T_1 - T}{10}}$$

- $L_1~:~$ Guaranteed life (h) at temperature, $T_1\ ^\circ \! C$
- L_2 : Expected life (h) at temperature, T_2 °C
- T_1 : Upper category temperature (°C)

L

T₂ : Actual operating temperature, ambient temperature + temperature rise due to ripple current heating(°C)

(4) Please use according to the lifetime as noted in this specification. Using products beyond end of the lifetime may change characteristics rapidly, short-circuit, operate pressure relief vent, or leak electrolyte.

| Engineering Draft | | | Guide | line-ALV-S1-4 | | |
|--|--------------------------------|-----------|----------|---------------|--|--|
| Application Guideline | es | | | Guidelines-2 | | |
| 1.3 Common Application Conditions to Avoid The following misapplication load conditions will cause rapid deterioration of a capacitor's electrical parameters. In addition, rapid heating and gas generation within the capacitor can occur, causing the pressure relief vent to operate and resultant leakage of electrolyte. Under extreme conditions, explosion and fire ignition could result. The leaked electrolyte is combustible and electrically conductive. (1) Reverse Voltage DC capacitors have polarity. Verify correct polarity before insertion. For circuits with changing or uncertain polarity, use DC bipolar capacitors. DC bipolar capacitors are not suitable for use in AC circuits. (2) Charge / Discharge Applications Standard capacitors are not suitable for use in repeating charge/discharge applications. For charge/ discharge applications, consult us with your actual application condition. (3) ON-OFF circuit Do not use capacitors in circuit where ON-OFF switching is repeated more than 10000 times/per day. In case of applying to the theses ON-OFF circuit, consult with us about circuit condition and so on. (4) Over voltage Do not apply voltages exceeding the maximum specified rated voltage. Voltages up to the surge voltage rating are acceptable for short periods of time. Ensure that the sum of the DC voltage and the superimposed AC ripple voltage does not exceed the rated voltage. (5) Ripple Current Do not apply vipple currents exceeding the maximum specified value. For high ripple current applications, use a capacitor designed for high ripple current is to be higher than the maximum specified value. | | | | | | |
| Ensure that rated ripple currents that superimposed on low DC bias voltages do not cause reverse voltage conditions. 1.4 Using Two or More Capacitors in Series or Parallel (1) Capacitors Connected in Parallel The circuit resistance can closely approximate the series resistance of the capacitor, causing an imbalance of ripple current loads within the capacitors. Careful wiring methods can minimize the possible application of an excessive ripple current to a capacitor. (2) Capacitors Connected in Series Differences in normal DC leakage current among capacitors can cause voltage imbalances. The use of voltage divider shunt resistors with consideration to leakage currents can prevent capacitor voltage imbalances. 1.5 Capacitor Mounting Considerations (1) Double-Sided Circuit Boards Avoid wiring pattern runs, which pass between the mounted capacitor and the circuit board. (2) Land/ Pad Pattern | | | | | | |
| | [Table of Board Land Siz | ze vs. Ca | apacitoi | [mm] | | |
| | Size / Dimension | а | b | c | | |
| | A (\$\phi\$3) | 0.6 | 2.2 | 1.5 | | |
| | B (<i>φ</i> 4) | 1.0 | 2.5 | 1.6 | | |
| | C (<i>φ</i> 5) | 1.5 | 2.8 | 1.6 | | |
| | D (\$\phi 6.3\$) | 1.8 | 3.2 | 1.6 | | |
| b a b | D8 (\$\$\phi 6.3\$\times 7.7L) | 1.8 | 3.2 | 1.6 | | |
| $\overset{\leftarrow}{\leftarrow} \overset{\ast}{}}}} \overset{\ast}{}} \overset{\ast}{}} \overset{\ast}{}}$ | E (φ8×6.2L) | 2.2 | 4.0 | 1.6 | | |
| | F (φ8×10.2L) | 3.1 | 4.0 | 2.0 | | |
| | G (φ10×10.2L) | 4.6 | 4.1 | 2.0 | | |
| | Η (φ12.5) | 4.0 | 5.7 | 2.0 | | |
| Land space | J (φ16) | 6.0 | 6.5 | 2.5 | | |
| | Κ (<i>φ</i> 18) | 6.0 | 7.5 | 2.5 | | |
| ※ The land pattern and size shall be decided in consideration of mountability, solderbility and strength. (3) Clearance for Case Mounted Pressure Relief (≥ φ 10 mm) Capacitors with case mounted pressure relief require sufficient clearance to allow for proper pressure relief operation. The minimum clearance are dependent on capacitor diameters as follows. (Dia 10mm ~ Dia 16mm : 2mm minimum , Dia 18mm : 3mm minimum) (4) Wiring Near the Pressure Relief (≥ φ 10 mm) Avoid locating high voltage or high current wiring or circuit board paths above the pressure relief . Flammable, high temperature gas that exceeds 100 ° C may be released which could dissolve the wire insulation and ignite. (5) Circuit Board Patterns Under the Capacitor Avoid circuit board runs under the capacitor, as an electrical short can occur due to an electrolyte leakage. 1.6 Electrical Isolation of the Capacitor Completely isolate the capacitor as follows. Between the cathode and the case and between the anode terminal and other circuit paths. 1.7 Capacitor Sleeve | | | | | | |
| The laminate coating is intended for marking and identification purposes and is not meant to electrically insulate the capacitor. | | | | | | |

| Engineering Draft | Guideline-ALV-S1-4 |
|--|---|
| Application Guidelines | Guidelines-3 |
| 2. Capacitor Handling Techniques 2.1 Considerations Before Using Capacitors have a finite life. Do not reuse or recycle capacitors from used equipment. Transient recovery voltage may be generated in the capacitor due to dielectric absorption. If required, this voltage can be discharged with a resistor with a value of about 1kΩ. Capacitors stored for a long period of time may exhibit an increase in leakage current. This can be corrected by gradually applying rated voltage in series with a resistor of approximately 1kΩ. If capacitors are dropped, they can be damaged mechanically or electrically. Avoid using dropped capacitors Dented or crushed capacitors should not be used. The seal integrity can be damaged and loss of electrolyte. 2. Capacitor Insertion Verify the correct polarity of the capacitor before insertion. Verify the correct hole spacing and land pattern size before insertion to avoid stress on the terminals. For chip type capacitors, excessive mounting pressure can cause high leakage current, short circuit, or discord. Werify the correct nult time soldering specifications or do not exceed temperature of 350 °C for 3 seconds If a soldered capacitor must be removed and reinserted, avoid excessive stress on the capacitor failure. 2.4 Reflow Soldering Surface-mount type capacitor are exclusively for reflow soldering. When reflow solder is used an ambient heat condition system such as the simultaneous use of infrared and head for the capacitor poper soldering conditions (temperature, the, etc.). Do not exceed the specified limits. To restrict the specified to poper soldering conditions (temperature, time, etc.). Do not exceed the specified limits. | /shortened life can result. nection. or less. ot-air is recommended. |
| (3) Reflow should be performed one time. Consult us for additional reflow restrictions. (4) In our recommended reflow condition, the case discoloration and the case swelling might be slightly generate But please acknowledge that these two phenomena do not influence the reliability of the product. (5) The crack on top marking might be occurred by reflow heat stress. But please acknowledge that it does not influence the reliability of the product. (6) VPS (Vapor Phase Soldering) reflow can cause significant characteristics change and/ or mounting failure due acute temperature rise. VPS is acceptable provided that the process does not exceed recommended reflow profile and temperature rise Please contact Panasonic for detailed conditions. | e to deformation by |
| 2.5 Capacitor Handling after Soldering (1) Avoid moving the capacitor after soldering to prevent excessive stress on the lead wires where they enter the s (2) Do not use the capacitor as a handle when moving the circuit board assembly. (3) Avoid striking the capacitor after assembly to prevent failure due to excessive shock. 2.6 Circuit Board Cleaning (1) Circuit boards can be immersed or ultrasonically cleaned using suitable cleaning solvents for up to 5 minutes | eal. |
| and up to 60 °C maximum temperatures. The boards should be thoroughly rinsed and dried. The use of ozone depleting cleaning agents is not recommended for the purpose of protecting our environment (2) Avoid using the following solvent groups unless specifically allowed in the specification ; Halogenated cleaning solvents : except for solvent resistant capacitor types, halogenated solvents can perminite internal capacitor corrosion and failure. For solvent resistant capacitors, carefully follow the temperature and time respecification. 1-1-1 trichloroethane should never be used on any aluminum Alkaline solvents : could react and dissolve the aluminum case. | eate the seal and cause equirements based on the |
| Petroleum based solvents Xylene Acetone deterioration of the rubber seal could result. removal of the ink markings on the vinyl sleeve could result. | |
| (3) A thorough drying after cleaning is required to remove residual cleaning solvents that may be trapped between board. Avoid drying temperatures, which exceed the Upper category temperature of the capacitor. (4) Monitor the contamination levels of the cleaning solvents during use in terms of electrical conductivity, pH, spec Chlorine levels can rise with contamination and adversely affect the performance of the capacitor. (5) Depending on the cleaning method, the marking on a capacitor may be erased or blurred. | |
| Please consult us if you are not certain about acceptable cleaning solvents or cleaning methods. | |
| 2.7 Mounting Adhesives and Coating Agents When using mounting adhesives or coating agents to control humidity, avoid using materials containing halogena Also, avoid the use of chloroprene based polymers. Harden on dry adhesive or coating agents well lest the solvent should be left. | ted solvents. |

After applying adhesives or coatings, dry thoroughly to prevent residual solvents from being trapped between the capacitor and the circuit board.

| Engineering Draft | Guideline-ALV-S1-4 |
|------------------------|--------------------|
| Application Guidelines | Guidelines-4 |

2.8 Fumigation

In exporting electronic appliances with aluminum electrolytic capacitors, in some cases fumigation treatment using such halogen compound as methyl bromide is conducted for wooden boxes.

If such boxes are not dried well, the halogen left in the box is dispersed while transported and enters in the capacitors inside.

This possibly causes electrical corrosion of the capacitors. Therefore, after performing fumigation and drying make sure that no halogen is left.

Don't perform fumigation treatment to the whole electronic appliances packed in a box.

3. Precautions for using capacitors

3.1 Environmental Conditions

Capacitors should not be stored or used in the following environments.

- (1) Exposure to temperatures above the upper category or below the lower category temperature of the capacitor.
- (2) Direct contact with water, salt water, or oil.
- (3) High humidity conditions where water could condense on the capacitor.
- (4) Exposure to toxic gases such as hydrogen sulfide, sulfuric acid, nitric acid, chlorine, Chlorine compound, Bromine, Bromine compound or ammonia.
- (5) Exposure to ozone, radiation, or ultraviolet rays.
- (6) Vibration and shock conditions exceeding specified requirements.

3.2 Electrical Precautions

- (1) Avoid touching the terminals of a capacitor as a possible electric shock could result. The exposed aluminum case is not insulated and could also cause electric shock if touched.
- (2) Avoid short circuiting the area between the capacitor terminals with conductive materials including liquids such as acids or alkaline solutions.
- (3) A low-molecular-weight-shiroxane which is included in a silicon material shall causes abnormal electrical characteristics.

4. Emergency Procedures

- (1) If the pressure relief of the capacitor operates, immediately turn off the equipment and disconnect from the power source. This will minimize an additional damage caused by the vaporizing electrolyte.
- (2) Avoid contact with the escaping electrolyte gas, which can exceed 100 °C temperatures.
- If electrolyte or gas enters the eye, immediately flush the eye with large amounts of water.
 - If electrolyte or gas is ingested by mouth, gargle with water.
 - If electrolyte contacts the skin, wash with soap and water.

5. Long Term Storage

Leakage current of a capacitor increases with long storage times. The aluminum oxide film deteriorates as a function of temperature and time. If used without reconditioning, an abnormally high current will be required to restore the oxide film.

This surge current could cause the circuit or the capacitor to fail.

Storage period is one year. When storage period is over 12 months, a capacitor should be reconditioned by applying the rated voltage in series with a 1000 Ω current limiting resistor for a time period of 30 minutes.

For storage condition, keep room temperature (5°C~35°C) and humidity (45%~85%) where direct sunshine doesn't reach.

5.1 Environmental Conditions

- (1) Exposure to temperatures above the upper category or below the lower category temperature of the capacitor.
- (2) Direct contact with water, salt water, or oil.
- (3) High humidity conditions where water could condense on the capacitor.
- (4) Exposure to toxic gases such as hydrogen sulfide, sulfuric acid, nitric acid, chlorine, Chlorine compound, Bromine, Bromine compound or ammonia.
- (5) Exposure to ozone, radiation, or ultraviolet rays.
- (6) Vibration and shock conditions exceeding specified requirements.

6. Capacitor Disposal

When disposing capacitors, use one of the following methods.

(1) Incinerate after crushing the capacitor or puncturing the can wall (to prevent explosion due to internal pressure rise).

(2) Dispose as solid waste.

NOTE : Local laws may have specific disposal requirements which must be followed.

单击下面可查看定价,库存,交付和生命周期等信息

>>Panasonic(松下)